Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.016”**

**.016”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .0065” X .0065”**

**Backside Potential: CATHODE**

**Mask Ref: CPD80V**

**APPROVED BY: DK DIE SIZE .016” X .016” DATE: 12/11/17**

**MFG: CENTRAL SEMI THICKNESS .007” P/N: CMPD2003**

**DG 10.1.2**

#### Rev B, 7/1